

# **BAP70-04W**

# Silicon PIN diode Rev. 01 — 5 March 2004

**Product data** 



### **Product profile**

#### 1.1 General description

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

#### 1.2 Features

- High voltage current control RF resistor for RF attenuators
- Low diode capacitance
- Low series inductance.

#### 1.3 Applications

RF attenuators and switches.

#### **Pinning information** 2.

Table 1: **Discrete pinning** 

Pin	Description	Simplified outline	Symbol		
1	anode	— .			
2	cathode	3	3		
3	common connection		2 1		
		1 2	sym015		
		sot323_so			

#### **Ordering information** 3.

Table 2: **Ordering information** 

Type number	Package			
	Name	Description	Version	
BAP70-04W	-	plastic surface mounted package; 3 leads	SOT323	





Table 3: Marking

Type number	Marking code
BAP70-04W	1Np

# 5. Limiting values

Table 4: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

		• • •			
Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
$V_R$	continuous reverse voltage		-	50	V
I <sub>F</sub>	continuous forward current		-	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> = 90 °C	-	260	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

#### 6. Thermal characteristics

Table 5: Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
$R_{th(j-s)}$	thermal resistance from junction to soldering point		230	K/W

#### 7. Characteristics

**Table 6: Characteristics** 

 $T_{amb}$  = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per diode						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA		0.95	1.1	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V		-	20	nA
C <sub>d</sub>	diode capacitance	see <u>Figure 1</u> ; f = 1 MHz;				
		V <sub>R</sub> = 0 V		600	-	fF
		V <sub>R</sub> = 1 V		430	-	fF
		V <sub>R</sub> = 20 V		250	300	fF

**Table 6:** Characteristics ...continued  $T_{amb} = 25 \,^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
r <sub>D</sub>	diode forward resistance	see Figure 2; f = 100 MHz;				
		I <sub>F</sub> = 0.5 mA		77	100	Ω
		I <sub>F</sub> = 1 mA		40	50	Ω
		I <sub>F</sub> = 10 mA		5.4	7	Ω
		I <sub>F</sub> = 100 mA		1.4	1.9	Ω
τ <sub>L</sub>	charge carrier life time	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 6 mA; R <sub>L</sub> = 100 $\Omega$ ; measured at I <sub>R</sub> = 3 mA		1.25	-	μs
L <sub>S</sub>	series inductance	$I_F = 100 \text{ mA}; f = 100 \text{ MHz}$		1.4	-	nΗ

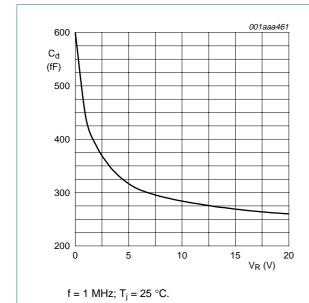


Fig 1. Diode capacitance as a function of reverse voltage; typical values.

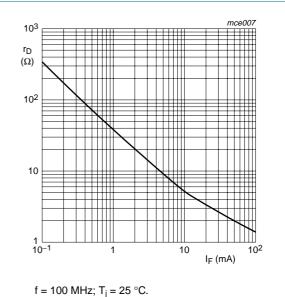


Fig 2. Forward resistance as a function of forward current; typical values.

## 8. Package outline

#### Plastic surface mounted package; 3 leads

**SOT323** 

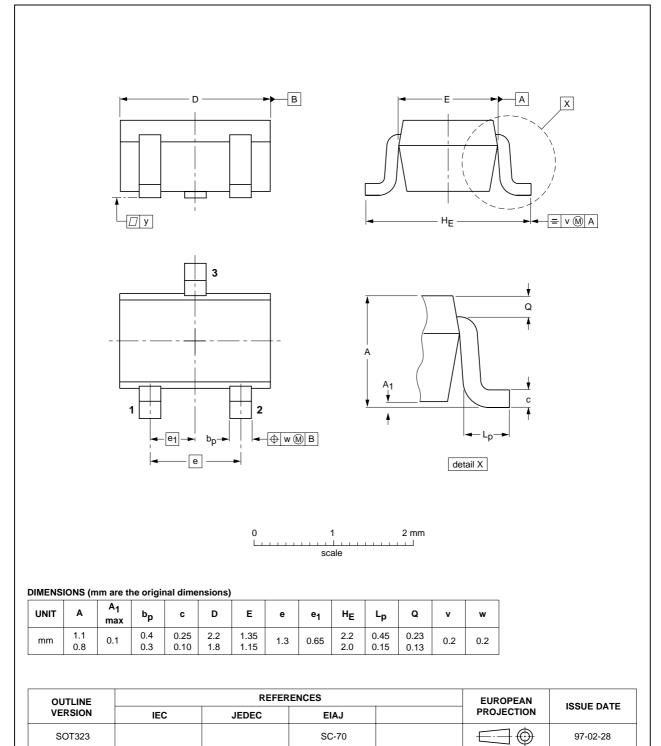


Fig 3. Package outline.





# 9. Revision history

#### Table 7: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
BAP70-04W_1	20040305	Product data	-	9397 750 12557	-



Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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